

## Description

This bipolar junction transistor (BJT) is designed to meet the stringent requirements of automotive applications.

## Features

- $BV_{CEO} > 160V$
- Ideal for Low Power Amplification and Switching
- Complementary PNP Type Available (MMBT5401)
- **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- **Halogen- and Antimony-Free. "Green" Device (Note 3)**
- **The MMBT5551Q is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF16949 certified facilities.**

<https://www.diodes.com/quality/product-definitions/>

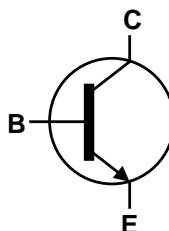
## Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish—Matte Tin Plated Leads Solderable per MIL-STD-202, Method 208 <sup>(e3)</sup>
- Weight: 0.008 grams (Approximate)

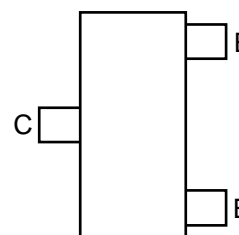
SOT23



Top View



Device Symbol



Top View  
Pin-Out

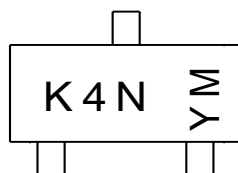
## Ordering Information (Note 4)

Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
MMBT5551Q-7	K4N	7	8	3,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information

SOT23



K4N = Product Type Marking Code  
YM = Date Code Marking  
Y = Year (ex: H = 2020)  
M = Month (ex: 9 = September)

### Date Code Key

Date Code Key

Year	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	H	I	J	K	L	M	N	O	P	R

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Absolute Maximum Ratings** (@  $T_A = +25^\circ\text{C}$  unless otherwise specified)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	180	V
Collector-Emitter Voltage	$V_{CEO}$	160	V
Emitter-Base Voltage	$V_{EBO}$	6.0	V
Continuous Collector Current (Note 5)	$I_C$	600	mA

**Thermal Characteristics** (@  $T_A = +25^\circ\text{C}$  unless otherwise specified)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	$P_D$	300	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	417	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**ESD Ratings** (Note 6)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
- For a device mounted on minimum recommended pad layout 1oz copper that is on a single-sided FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
  - Refer to JEDEC specification JESD22-A114 and JESD22-A115.

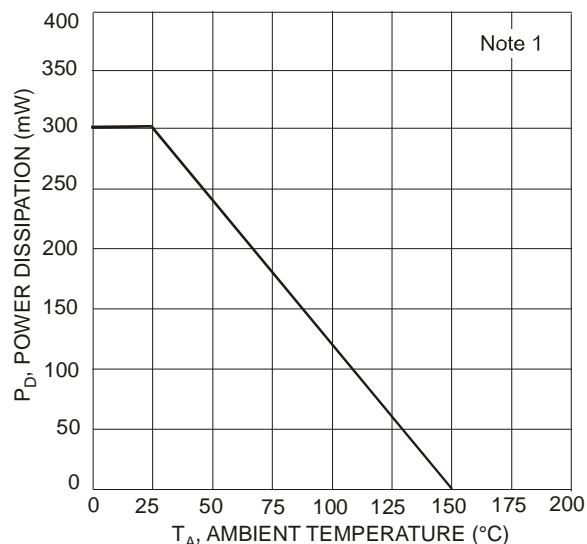


Fig. 1 Power Dissipation vs. Ambient Temperature

**Electrical Characteristics** @  $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 7)</b>					
Collector-Base Breakdown Voltage	$BV_{CBO}$	180	—	V	$I_C = 100\mu\text{A}$ , $I_E = 0$
Collector-Emitter Breakdown Voltage	$BV_{CEO}$	160	—	V	$I_C = 1.0\text{mA}$ , $I_B = 0$
Emitter-Base Breakdown Voltage	$BV_{EBO}$	6.0	—	V	$I_E = 10\mu\text{A}$ , $I_C = 0$
Collector Cutoff Current	$I_{CBO}$	—	50	nA $\mu\text{A}$	$V_{CB} = 120\text{V}$ , $I_E = 0$ $V_{CB} = 120\text{V}$ , $I_E = 0$ , $T_A = 100^\circ\text{C}$
Emitter Cutoff Current	$I_{EBO}$	—	50	nA	$V_{EB} = 4.0\text{V}$ , $I_C = 0$
<b>ON CHARACTERISTICS (Note 7)</b>					
DC Current Gain	$h_{FE}$	80 80 30	— 250 —	—	$I_C = 1.0\text{mA}$ , $V_{CE} = 5.0\text{V}$ $I_C = 10\text{mA}$ , $V_{CE} = 5.0\text{V}$ $I_C = 50\text{mA}$ , $V_{CE} = 5.0\text{V}$
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	—	0.15 0.20	V	$I_C = 10\text{mA}$ , $I_B = 1.0\text{mA}$ $I_C = 50\text{mA}$ , $I_B = 5.0\text{mA}$
Base-Emitter Saturation Voltage	$V_{BE(sat)}$	—	1.0	V	$I_C = 10\text{mA}$ , $I_B = 1.0\text{mA}$ $I_C = 50\text{mA}$ , $I_B = 5.0\text{mA}$
<b>SMALL SIGNAL CHARACTERISTICS</b>					
Output Capacitance	$C_{obo}$	—	6.0	pF	$V_{CB} = 10\text{V}$ , $f = 1.0\text{MHz}$ , $I_E = 0$
Small Signal Current Gain	$h_{fe}$	50	250	—	$V_{CE} = 10\text{V}$ , $I_C = 1.0\text{mA}$ , $f = 1.0\text{kHz}$
Current Gain-Bandwidth Product	$f_t$	100	300	MHz	$V_{CE} = 10\text{V}$ , $I_C = 10\text{mA}$ , $f = 100\text{MHz}$
Noise Figure	nf	—	8.0	dB	$V_{CE} = 5.0\text{V}$ , $I_C = 200\mu\text{A}$ , $R_S = 1.0\text{k}\Omega$ , $f = 1.0\text{kHz}$

Notes: 7. Measured under pulsed conditions. Pulse width  $\leq 300\mu\text{s}$ . Duty cycle  $\leq 2\%$ .

**Typical Electrical Characteristics** (@  $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

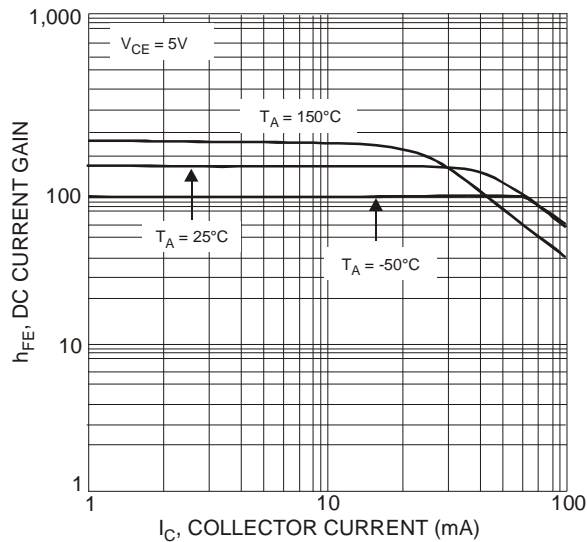


Fig. 2 Typical DC Current Gain vs. Collector Current

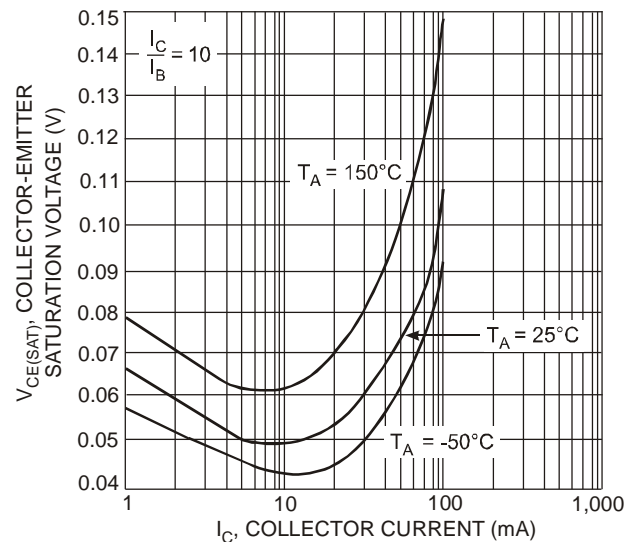


Fig. 3 Typical Collector-Emitter Saturation Voltage vs. Collector Current

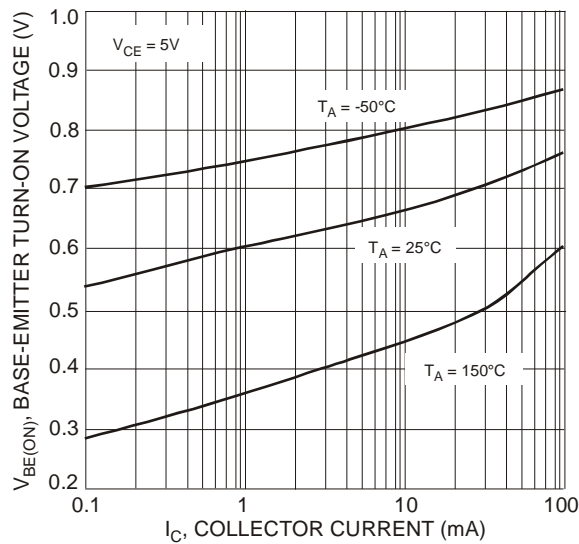


Fig. 4 Typical Base-Emitter Turn-On Voltage vs. Collector Current

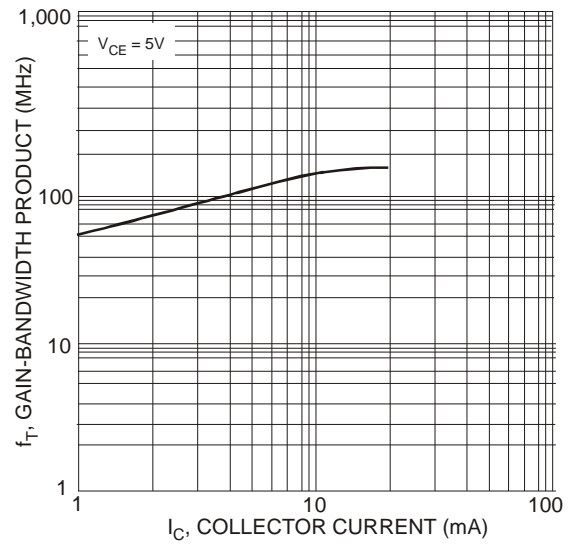
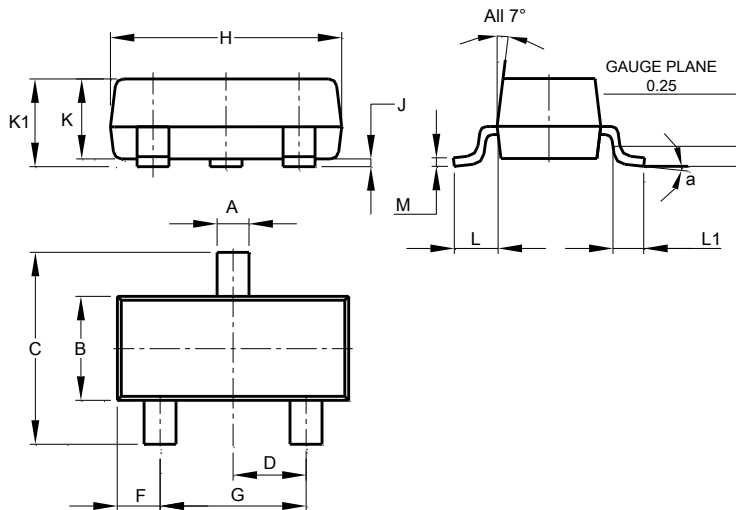


Fig. 5 Typical Gain-Bandwidth Product vs. Collector Current

## Package Outline Dimensions

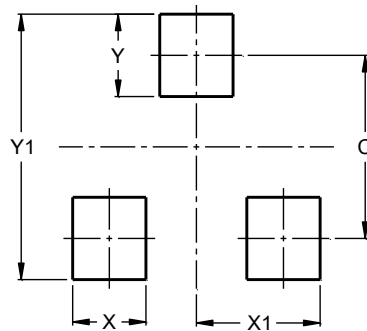
Please see <http://www.diodes.com/package-outlines.html> for the latest version.



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	0°	8°	--
All Dimensions in mm			

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



Dimensions	Value (in mm)
C	2.0
X	0.8
X1	1.35
Y	0.9
Y1	2.9

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